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				APPLICANT Koyu ASAI, et al.			
(PTO-1449)				FILING DATE December 03, 2003	GRC	OUP	
	_		U.S. PATENT	DOCUMENTS			
EXAMINER'S INITIALS	CITE NO.	Document Number Number-Kind Codez (1 known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document		Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
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W	 	JP 7-106323 JP 9-213800	04/21/1995 08/15/1997	NEC CORP		(Japan w/English Abstract) (Japan w/English Abstract)	+
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EXAMINER'S INITIALS	CITE NO.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate),ook, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.					
S		"Stress-Induced Voiding Under Vias Connected to Wide Cu Metal Leads", E.T. Ogawa et al., 2002 IEEE International Reliability Physics Symposium Proceedings, April 7-11, 2002.					
P		"Mechanisms of Stress-Induced Voids in Multi-Level Cu Interconnects", Byung-Lyul Park et al., IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002.					
B		Thermal Stress of 140nm-width Cu damascene interconnects, Norio Økada et al., IEEE 2002 International Interconnect Technology Conference, June 3/5, 2002.					
		EXAMINER		02/20/2	DATE CONSIDI	ERED	
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